

Title (en)  
Free-cutting copper alloys

Title (de)  
Automatenlegierung auf Kupferbasis.

Title (fr)  
Alliage de décolletage à base de cuivre.

Publication  
**EP 1508626 A1 20050223 (EN)**

Application  
**EP 04077561 A 19981116**

Priority  
• EP 98953070 A 19981116  
• JP 28792198 A 19981009

Abstract (en)  
Free-cutting alloys with industrially satisfactory machinability comprising 69 to 79 percent, by weight, of copper, 2.0 to 4.0 percent, by weight, of silicon; 0.02 to 0.4, by weight, of lead and the remaining percent, by weight, of zinc. <IMAGE>

IPC 1-7  
**C22C 9/04**; **C22F 1/08**

IPC 8 full level  
**C22F 1/00** (2006.01); **C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)  
**C22C 9/04** (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP)

Citation (search report)  
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Designated contracting state (EPC)  
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